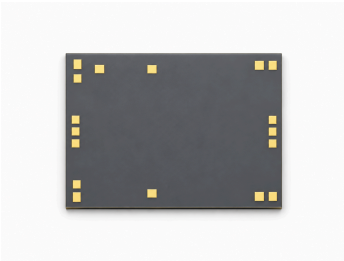


13000–15000 MHz GaN MMIC Power Amplifier Die

pulsed: PSAT: 42 dBm (typical); Power gain: 21 dB (typical); PAE: 35 % (minimum) / 37 % (typical). Die dimensions: 2.8 × 2 × 0.1 mm.



RF characteristics · TA = +25 °C; Vd = +28 V; Vg = -3.05 V; pulsed

Parameter	Symbol	Minimum	Typical	Maximum	Value	Unit
Operating frequency	f	13000	-	15000	13000–15000	MHz
Saturated output power	Psat	-	42	-	-	dBm
Power gain	Gp	-	21	-	-	dB
Power-gain flatness	ΔGp	-	±0.35	-	-	dB
Power-added efficiency	PAE	35	37	-	-	%
Input VSWR	VSWR(in)	-	1.8	-	-	-

DC bias and current · TA = +25 °C

Parameter	Symbol	Minimum	Typical	Maximum	Unit
Drain voltage	Vd	24	28	32	V
Gate voltage	Vg	-5	-3.05	-2.6	V
Quiescent drain current	Id	-	0.11	-	A
Dynamic drain current	Idd	-	1.7	-	A
Dynamic gate current	Igg	-	0.5	-	mA

Absolute limits

Parameter	Symbol	Minimum	Typical	Maximum	Unit
Maximum drain-source voltage	Vd	-	-	32	V
Minimum gate bias	Vg	-5	-	-	V
Maximum input power	Pin	-	-	24	dBm
Storage temperature	TSTG	-65	-	150	°C
Maximum channel temperature	Top	-	-	225	°C

Die dimensions

Parameter	Value	Unit
Die dimensions	$2.8 \times 2 \times 0.1$	mm

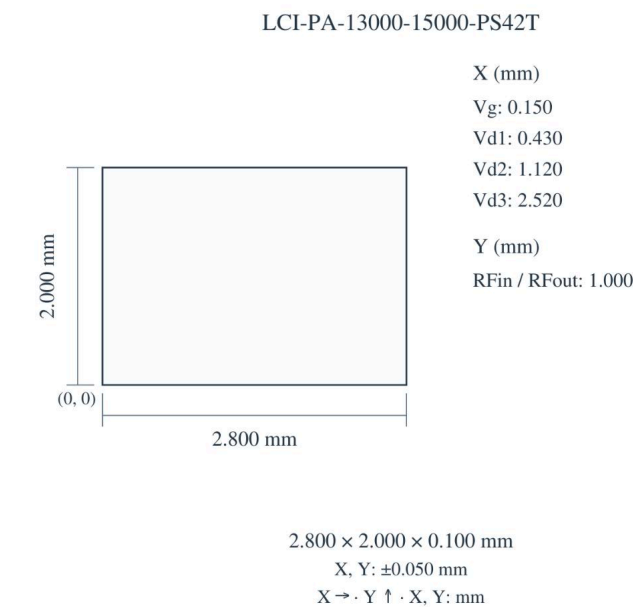
Die integration and bias sequencing

Integrated DC blocking: RFin / RFout. DC path to ground: RFin → GND. Separate characterization: Vd = +28 V; Vg = -3.05 V; CW; Pin = 21 dBm. Apply gate bias before drain bias. Remove drain bias before gate bias. Two-sided bias feed is recommended.

Mechanical reference scope

Source-based outline and explicitly dimensioned coordinate guides in mm. Not a complete fabrication or wire-bonding drawing.

Mechanical Outline



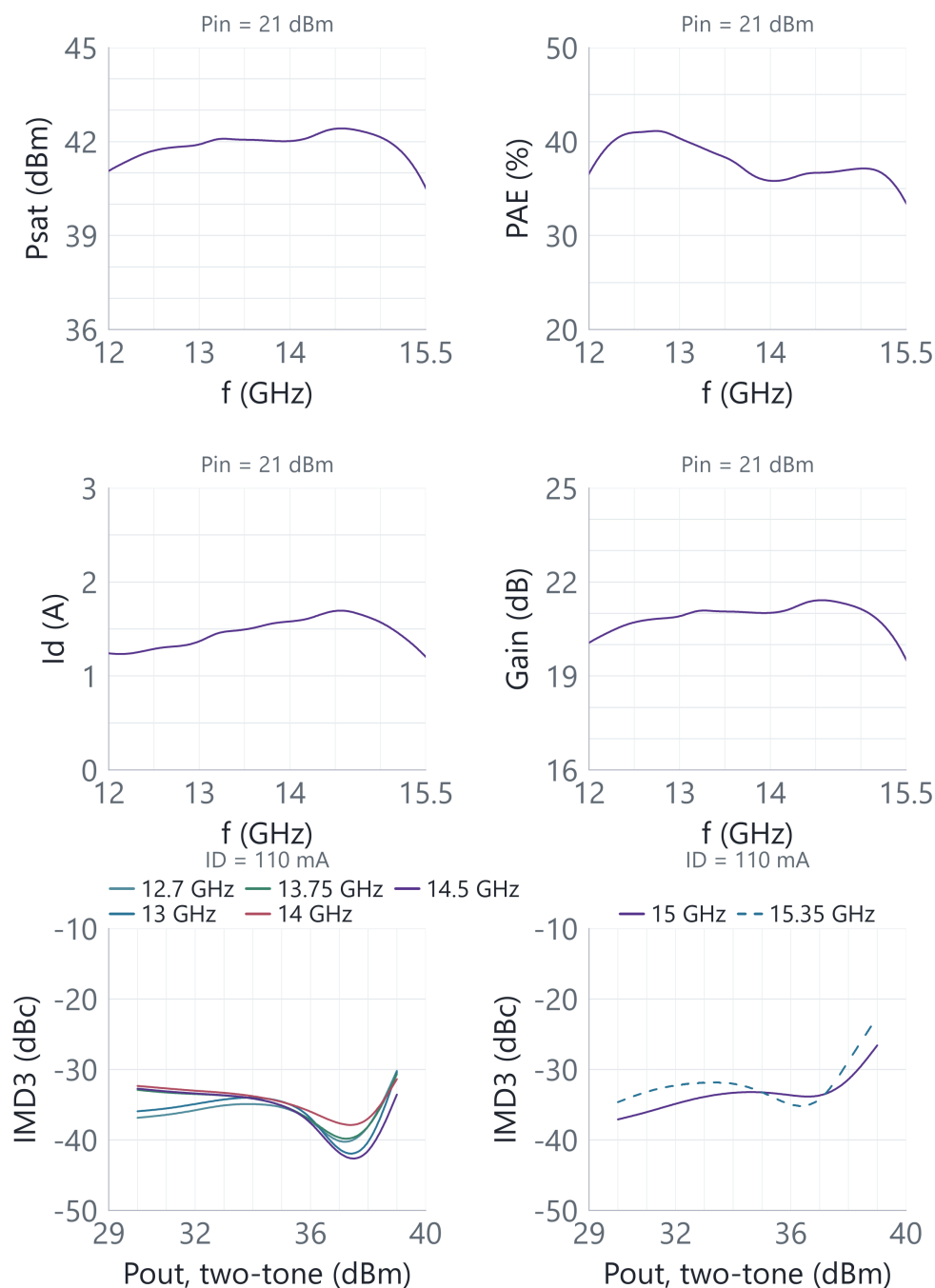
All dimensions are in mm [in].

Performance curves

Plots from the source datasheet. Read each figure with its stated operating conditions.

Saturated output power; Power-added efficiency; Dynamic drain current; Power gain; IMD3.

Source-page annotation: $V_d=+28V$; $V_g=-3.05V$. Redrawn from the source figure; readings are approximate. Psat/PAE/Id/Gain: Pin = 21 dBm. IMD3: Id = 110 mA.



[Source](#)

Document notice

Specifications are subject to revision. Before design release, confirm the current document revision and product-specific requirements with LCRF. The approved quotation and order documentation define the supplied configuration.